

SEMITRANS[®] 6

Standard IGBT modules

SKM 40GD123D SKM 40GDL123D

Features

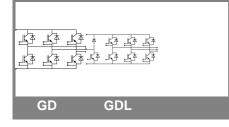
- MOS input (voltage controlled)
- N channel, homogeneous Si
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology
- Large clearance (9 mm) and creepage distances (13 mm)

Typical Applications

- Switched mode power supplies
- Three phase inverters for AC motor speed control
- Pulse frequencies also above 15 kHz

Absolute Maximum Ratings $T_c = 25$ °C, unless otherwise specified					
Symbol	Conditions		Values	Units	
IGBT		·			
V _{CES}	T _j = 25 °C		1200	V	
I _C	T _j = 150 °C	T _{case} = 25 °C	40	А	
		T _{case} = 80 °C	30	А	
I _{CRM}	I _{CRM} =2xI _{Cnom}		50	А	
V _{GES}			± 20	V	
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; VCES < 1200 V	T _j = 125 °C	10	μs	
Inverse	Diode			•	
I _F	T _j = 150 °C	T _{case} = 25 °C	45	А	
		T _{case} = 80 °C	30	А	
I _{FRM}	I _{FRM} =2xI _{Fnom}		50	А	
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	350	А	
Module	·	÷			
I _{t(RMS)}			100	А	
T _{vj}			- 40+ 150	°C	
T _{stg}			- 40+ 125	°C	
V _{isol}	AC, 1 min.		2500	V	

Characteristics T _c =			25 °C, unless otherwise specified			
Symbol IGBT	Conditions		min.	typ.	max.	Units
V _{GE(th)}	V_{GE} = V_{CE} , I_C = 1 mA		4,5	5,5	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _i = 25 °C		0,3	0,9	mA
V _{CE0}		T _i = 25 °C		1,4	1,6	V
		T _j = 125 °C		1,6	1,8	V
r _{CE}	V _{GE} = 15 V	T _i = 25°C		44	56	mΩ
		T _j = 125°C		60	76	mΩ
V _{CE(sat)}	I _{Cnom} = 25 A, V _{GE} = 15 V	$T_j = °C_{chiplev.}$		2,5	3	V
C _{ies}				1,6	2,1	nF
C _{oes}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		0,25	0,3	nF
C _{res}				0,11	0,15	nF
t _{d(on)}				70		ns
t, Ó	R _{Gon} = 40 Ω	V _{CC} = 600V		55		ns
E _{on}		I _{Cnom} = 25A		3,8		mJ
t _{d(off)}	R _{Goff} = 40 Ω	T _i = 125 °C		400		ns
t _f		V _{GE} = -15V		40		ns
E _{off}		-		2,3		mJ
R _{th(j-c)}	per IGBT	·			0,56	K/W





SEMITRANS[®] 6

Standard IGBT modules

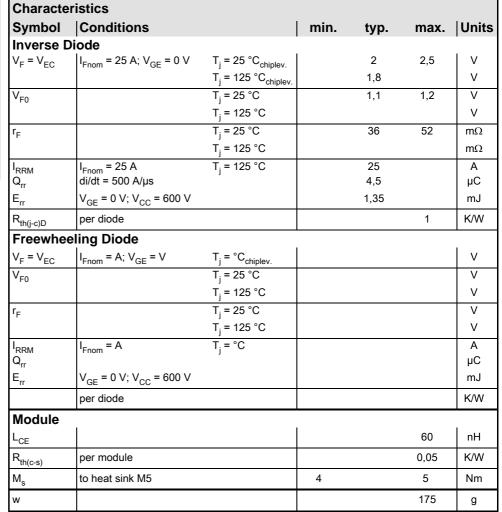
SKM 40GD123D SKM 40GDL123D

Features

- MOS input (voltage controlled)
- N channel, homogeneous Si
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology
- Large clearance (9 mm) and creepage distances (13 mm)

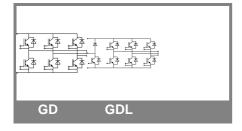
Typical Applications

- Switched mode power supplies
- Three phase inverters for AC motor speed control
- Pulse frequencies also above 15 kHz



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.





Standard IGBT modules

SKM 40GD123D SKM 40GDL123D

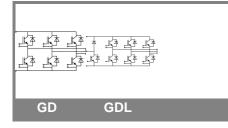
Z _{th}	Conditions	Values	
Symbol	Conditions	Values	Units
Z _{th(j-c)} l			
Ri	i = 1	260	mk/W
R _i	i = 2	250	mk/W
R _i	i = 3	38	mk/W
R _i	i = 4	12	mk/W
tau _i	i = 1	0,0447	S
tau	i = 2	0,0079	S
tau	i = 3	0,0015	S
tau _i	i = 4	0,0002	s
Z _{Ri} th(j-c)D			
R _i	i = 1	580	mk/W
R _i	i = 2	330	mk/W
R _i	i = 3	73	mk/W
R _i	i = 4	17	mk/W
tau	i = 1	0,054	S
taui	i = 2	0,0089	s
tau	i = 3	0,0018	s
tau _i	i = 4	0,0002	s

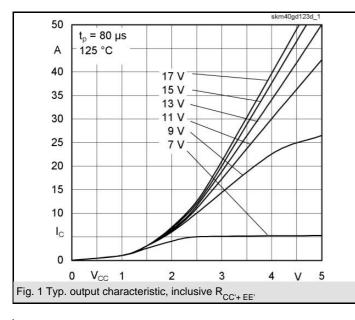
Features

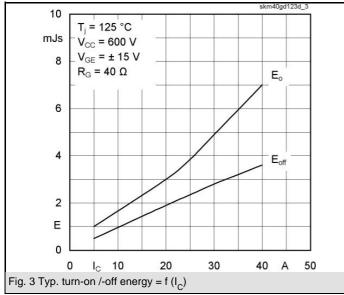
- MOS input (voltage controlled)
- N channel, homogeneous Si
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology
- Large clearance (9 mm) and creepage distances (13 mm)

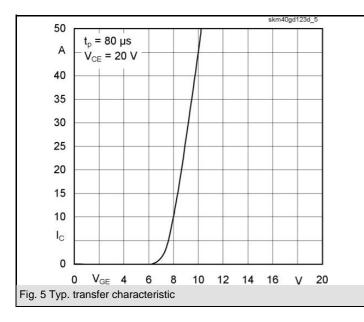
Typical Applications

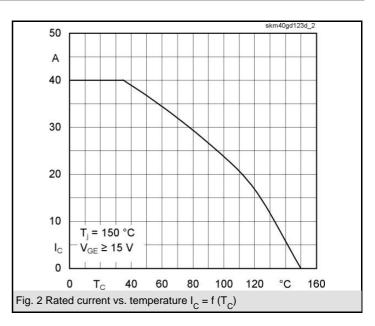
- Switched mode power supplies
- Three phase inverters for AC motor speed control
- Pulse frequencies also above 15 kHz

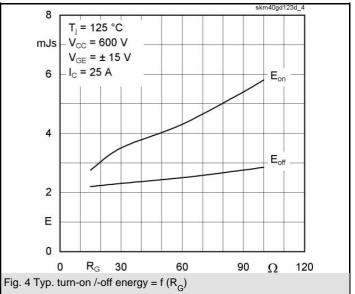


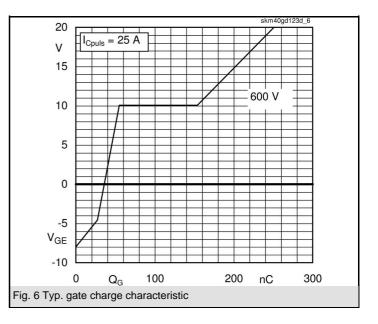


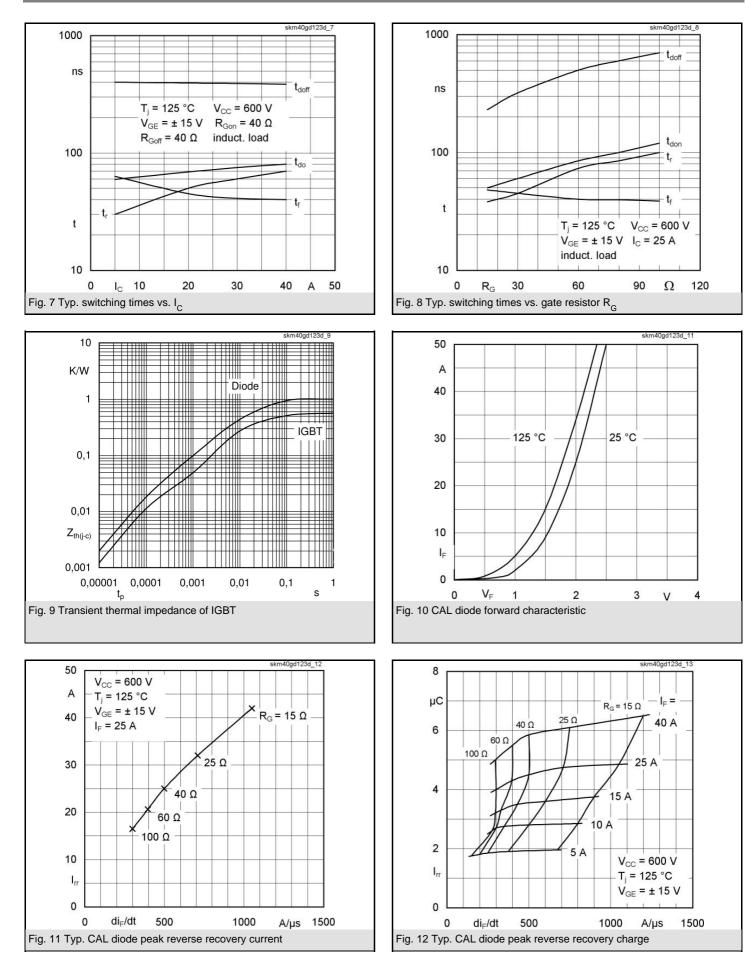












19-10-2006 RAA

